



Material Content Data Sheet



Sales Product Name		TLE7268SK		Issued		24. January 2018		
MA#		MA001687200						
Package		PG-DSO-14-45		Weight*		142.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.475	1.04	1.04	10354	10354
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		106	
	non noble metal	zinc	7440-66-6	0.060	0.04		424	
	non noble metal	iron	7439-89-6	1.207	0.85		8471	
wire	non noble metal	copper	7440-50-8	49.007	34.40	35.30	343954	352955
	non noble metal	copper	7440-50-8	0.103	0.07	0.07	720	720
	encapsulation	organic material	carbon black	1333-86-4	0.176	0.12		1233
	plastics	epoxy resin	-	8.084	5.67		56735	
	inorganic material	silicondioxide	60676-86-0	79.607	55.87	61.66	558719	616687
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8606	8606
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7227	7227
glue	plastics	acrylic resin	-	0.108	0.08		759	
	noble metal	silver	7440-22-4	0.384	0.27	0.35	2692	3451
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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